

semiconductor chip has been bonded to the support member.

62. (NEW) A semiconductor device comprising a support member, a semiconductor chip, an attaching member for attaching the semiconductor chip to the support member, and an encapsulant resin encapsulating the support member, the semiconductor chip and the attaching member, wherein:

the attaching member is a cured product of a die-bonding material;

the die-bonding material is a film comprising one or more resins selected from the group consisting of silicone resin, acrylic resin, polyimide resin and epoxy resin; and

the film i) has a planar dimension not larger than a planar dimension of the semiconductor chip, and ii) is not protruding outward from a region of the semiconductor chip at a stage where the semiconductor chip has been bonded to the support member.